

Amendments to the Claims:

The following Listing of Claims replaces all prior versions and listings of the claims in this application.

Listing of Claims:

Claims 1-15 (Cancelled).

Claim 16 (Original): A dry film formed from a curable resin composition comprising a polymer having a number average molecular weight within a range of 1,000 to 1,000,000 as measured by gel permeation chromatography, and a hardener.

Claim 17 (Original): The dry film according to Claim 16, wherein the cycloolefin polymer contains at least 50 mol% of a repeating unit derived from a cycloolefin monomer and has a glass transition temperature of at least 100°C as measured by a differential scanning calorimeter.

Claim 18 (Original): The dry film according to Claim 16, wherein the cycloolefin polymer has a polar group.

Claim 19 (Original): The dry film according to Claim 16, wherein the curable resin composition is a varnish further comprising an organic solvent.

Claim 20 (Original): A process for producing a dry film, the process comprising the steps of applying a curable resin composition comprising a cycloolefin polymer having a number average molecular weight within a range of 1,000 to 1,000,000 as measured by gel

permeation chromatography, a hardener and a solvent to a substrate and removing the organic solvent under conditions that a curing reaction of the curable resin composition is not caused to completely proceed.

Claim 21 (Original): A laminate comprising an insulating layer formed with a dry film formed from a curable resin composition comprising a polymer having a number average molecular weight within a range of 1,000 to 1,000,000 as measured by gel permeation chromatography, and a hardener, and a conductive layer formed on the surface of the insulating layer.

Claim 22 (Original): A multi-layer laminate further comprising each at least one insulating layer formed with the dry film and conductive layer on the conductive layer-forming surface of the laminate according to Claim 21, wherein the conductive layers are connected to each other by forming interlayer-connecting via holes in the insulating layer provided between them.

Claim 23 (Original): A process for producing a multi-layer laminate, which comprises a step (A) of laminating a dry film formed from a curable resin composition comprising a polymer having a number average molecular weight within a range of 1,000 to 1,000,000 as measured by gel permeation chromatography, and a hardener on at least one side of a substrate, conducting the curing of the dry film and the formation of interlayer-connecting via holes, and then forming a conductive layer on the surface of the dry film and wall surfaces of the via holes to produce a laminate, and a step (B) of laminating an additional dry film on the conductive layer-forming surface of the laminate to conduct the curing of the

dry film, formation of interlayer-connecting via holes and formation of a conductive layer in the same manner as in the step (A), wherein the step (B) is repeated at least once.

Claims 24-30 (Cancelled).